

APPARATUS FOR ALIGNING AND
DISPENSING SOLDER COLUMNS IN AN ARRAY

ABSTRACT OF THE DISCLOSURE

5 An apparatus for aligning and dispensing a plurality
of solder columns in an array. The apparatus includes a
vibrator and an elongated alignment plate supported on the
vibrator. The alignment plate includes a plurality of
longitudinal guide grooves. A transparent cover is secured
on the alignment plate and shaped to cover part of the
10 guide grooves. A parts feeder is operatively associated
with the alignment plate to feed solder columns over the
upstream end of the alignment plate. The solder columns
are received in the guide grooves and fed toward the
downstream end of the alignment plate while the alignment
15 plate is vibrated by the vibrator. The solder columns are
arranged in an array within the guide grooves so that a
vacuum pickup tool may readily capture the cylindrical body
of the solder columns.